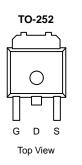


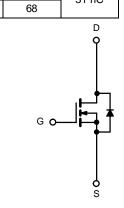
RoHS

COMPLIANT

35N03-VB Datasheet N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{a, e}	Q _g (Typ)			
30	0.005 at V _{GS} = 10 V	80	31 nC			
30	0.006 at V _{GS} = 4.5 V	68	31110			
			D			





N-Channel MOSFET

FEATURES

- ٠ Trench Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2011/65/EU ٠

APPLICATIONS

- OR-ing
- Server
- DC/DC

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage		V _{GS}		± 20	
	T _C = 25 °C		80		
Continuous Drain Current (T $= 175$ °C)	T _C = 70 °C		60		
Continuous Drain Current ($T_J = 175 \ ^{\circ}C$)	T _A = 25 °C	I _D	25.8 ^{b, c}	A	
	T _A = 70 °C		22 ^{b, c}		
Pulsed Drain Current		I _{DM}	250		
Avalanche Current Pulse	e L = 0.1 mH		39		
Single Pulse Avalanche Energy	L = 0.1 mm	E _{AS}	94.8	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	1	90 ^{a, e}	٨	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.13 ^{b, c}	— A	
	T _C = 25 °C		205 ^a		
Mauianum Davier Diasis ation	T _C = 70 °C	Р	135	10/	
Maximum Power Dissipation	T _A = 25 °C	P _D	3.75 ^{b, c}		
	T _A = 70 °C		2.63 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Тур.	Max.	Unit	
Maximum Junction-to-Ambient ^{b, d}	$t \le 10 \text{ sec}$	R _{thJA}	32	40	°C/W	
Maximum Junction-to-Case	Steady State	R _{thJC}	0.5	0.6	°C/W	

Notes:

a. Based on $T_C = 25 \text{ °C}$. b. Surface mounted on 1" x 1" FR4 board.

a. t = 10 sec.
d. Maximum under steady state conditions is 90 °C/W.
e. Calculated based on maximum junction temperature. Package limitation current is 90 A.

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	· ·						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$				V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		35		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$		- 7.5		mv/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.0		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, \text{ V}_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 30 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			А	
		V _{GS} = 10 V, I _D = 38.8 A		0.005		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 37 \text{ A}$		0.006			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 38.8 A		160		S	
Dynamic ^b	11				<u> </u>	<u> </u>	
Input Capacitance	C _{iss}			2201		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		525			
Reverse Transfer Capacitance	C _{rss}			270			
Total Gate Charge	0	V_{DS} = 15 V, V_{GS} = 10 V, I_{D} = 38.8 A		61	107		
	Qg			31.5	50	nC	
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 28.8 A		10			
Gate-Drain Charge	Q _{gd}			6			
Gate Resistance	Rg	f = 1 MHz		1.4	2.1	Ω	
Turn-On Delay Time	t _{d(on)}			18	27		
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.625 Ω		11	17	- ns -	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 24 A, V_{GEN} = 10 V, R_g = 1 Ω		70	105		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			55	83		
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.67 Ω		180	270		
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}{\cong}22.5$ A, V_GEN = 4.5 V, R_g = 1 Ω		55	83		
Fall Time	t _f			12	18		
Drain-Source Body Diode Characteristic	s				1	1	
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			120	•	
Pulse Diode Forward Current ^a	I _{SM}				120	A	
Body Diode Voltage	V _{SD}	I _S = 22 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			52	78	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			70.2	105	nC	
Reverse Recovery Fall Time	t _a	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^\circ\text{C}$		27			
Reverse Recovery Rise Time	t _b			25		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

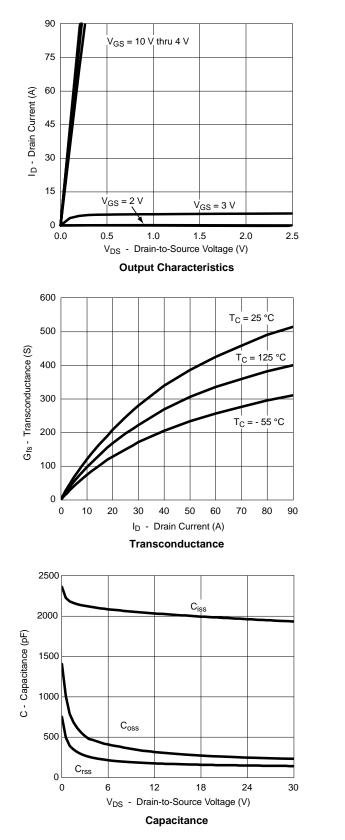
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

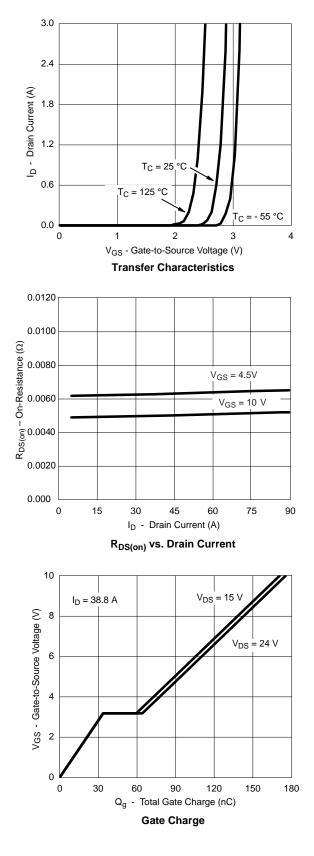
semi

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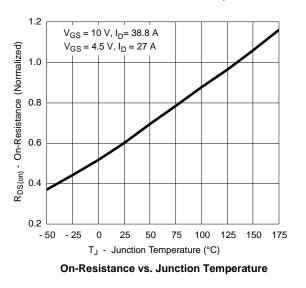




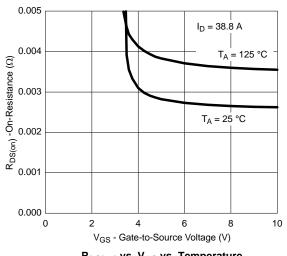
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

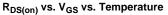


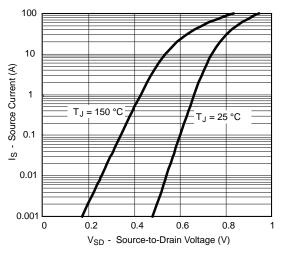




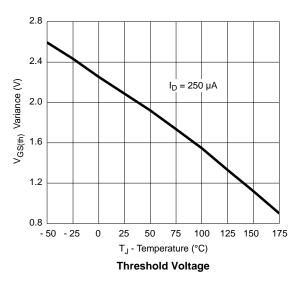
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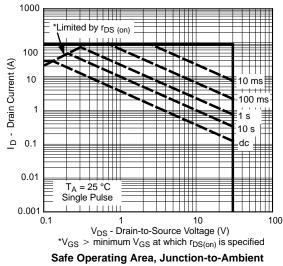




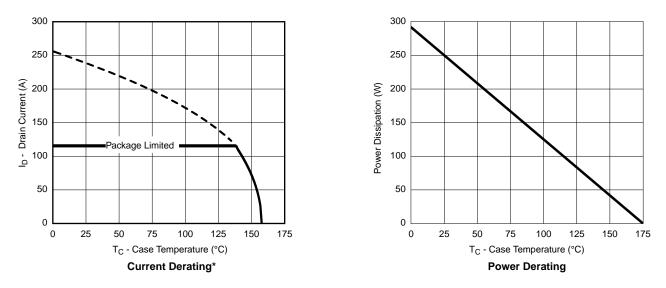


Forward Diode Voltage vs. Temperature









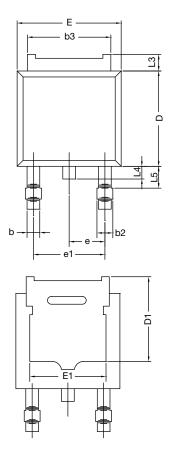
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

*The power dissipation P_D is based on $T_{J(max)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





TO-252AA CASE OUTLINE





	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
E	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347					

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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